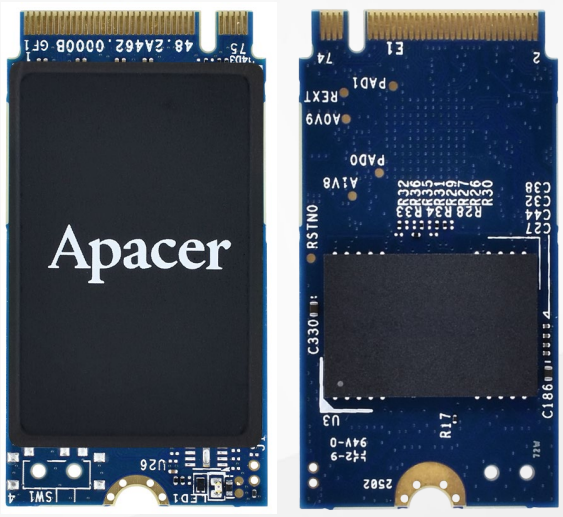
Apacer

RoHS Compliant

PCI Express Flash Drive

Industrial PT230-M242 BiCS5 Product Specifications



April 27, 2026

Version 1.4

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Specifications Overview:

- **PCIe Interface**
  - Compliant with PCI Express 3.1
  - Compliant with NVMe 1.4
  - Compatible with PCIe Gen3 x4 interface
- **Capacity**
  - Single-sided: 64, 128 GB
  - Double-sided: 256, 512 GB / 1 TB
- **Performance**[1]
  - Interface burst read/write: 4 GB/sec
  - Sequential read: up to 3,650 MB/sec
  - Sequential write: up to 2,550 MB/sec
  - Random read (4K): up to 328,000 IOPS
  - Random write (4K): up to 297,000 IOPS
- **Flash Management**
  - Error Correction/Detection
  - Bad Block Management
  - Global Wear Leveling
  - DataDefender™
  - TRIM
  - Flash Translation Layer: Page Mapping
  - Hyper Cache Technology
  - DataRAID™
  - Smart Read Refresh™
  - S.M.A.R.T.
- **NVMe Features**
  - NVMe Secure Erase
  - Supports HMB (Host Memory Buffer)[2]
- **NAND Flash Type:** 3D TLC (BiCS5)
- **MTBF:** >3,000,000 hours
- **Endurance (in drive writes per day: DWPD)**
  - 64 GB: 2.28 DWPD
  - 128 GB: 2.05 DWPD
  - 256 GB: 2.17 DWPD
  - 512 GB: 2.01 DWPD
  - 1 TB: 1.99 DWPD
- **Temperature Range**
  - Operating (Tc): 0°C to 70°C
  - Storage (Ta): -55°C to 100°C
- **Supply Voltage**
  - 3.3V ± 5%
- **Power Consumption**[1]
  - Active mode (Max.): 1,230 mA
  - Idle mode: 200 mA
- **Power Management**
  - Supports APST
  - Supports ASPM L1.2
- **Security**
  - AES 256-bit hardware encryption
- **Reliability**
  - Thermal Sensor
  - Thermal Throttling
  - End-to-End Data Protection
  - Sidefill
  - Heat Spreader
- **Connector Type**
  - 75-pin M.2 module pinout
- **Physical Characteristics**
  - Form factor:
    - Single-sided: M.2 2242-M
    - Double-sided: M.2 2242-M
  - Dimensions (unit: mm):
    - Single-sided: 22.00 x 42.00 x 2.58(max.)
    - Double-sided: 22.00 x 42.00 x 4.08(max.)
- **LED Indicator for Drive Behavior**
- **RoHS Compliant**

Notes:
1. Varies from capacities. The values for performance and power consumption presented are typical and may vary depending on flash configurations or platform settings. The term idle refers to the standby state of the device.
2. Windows 10 (version 1703) onwards supports the HMB (Host Memory Buffer) function.

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Table of Contents

1. General Description 4

2. Functional Block 4

3. Pin Assignments 5

4. Product Specifications 8

4.1 Capacity 8
4.2 Performance 8
4.3 Environmental Specifications 8
4.4 Mean Time Between Failures (MTBF) 9
4.5 Certification and Compliance 9
4.6 Endurance 9
4.7 LED Indicator Behavior 10

5. Flash Management 11

5.1 Error Correction/Detection 11
5.2 Bad Block Management 11
5.3 Global Wear Leveling 11
5.4 DataDefender™ 11
5.5 TRIM 11
5.6 Flash Translation Layer – Page Mapping 12
5.7 Hyper Cache Technology 12
5.8 DataRAID™ 12
5.9 Smart Read Refresh™ 12

6. NVMe Support Features 13

6.1 NVMe Secure Erase 13
6.2 Host Memory Buffer 13

7. Security and Reliability Features 14

7.1 Advanced Encryption Standard 14
7.2 Thermal Sensor 14
7.3 Thermal Throttling 14
7.4 End-to-End Data Protection 14
7.5 Sidefill 14
7.6 Heat Spreader 15

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8. Software Interface 16

8.1 Command Set 16

8.2 S.M.A.R.T. 17

9. Electrical Specifications 19

9.1 Operating Voltage 19

9.2 Power Consumption 19

10. Mechanical Specifications 20

10.1 Single-sided Dimensions 20

10.2 Double-sided Dimensions 21

11. Product Ordering Information 22

11.1 Product Code Designations 22

11.2 Valid Combinations 22

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1. General Description

Apacer PT230-M242 is a high-performance SSD designed in M.2 2242 mechanical dimensions, offering full compliance with PCIe Gen3 x4 interface and NVMe 1.4 specifications. It supports power management modes, significantly reducing power consumption. Built with a powerful PCIe controller that features on-the-module ECC and an efficient wear leveling scheme, PT230-M242 delivers exceptionally low latency and outstanding data transfer performance. Its compact design and high-speed storage make it the ideal choice for larger, faster hosts deployed across a wide range of applications requiring top-tier performance.

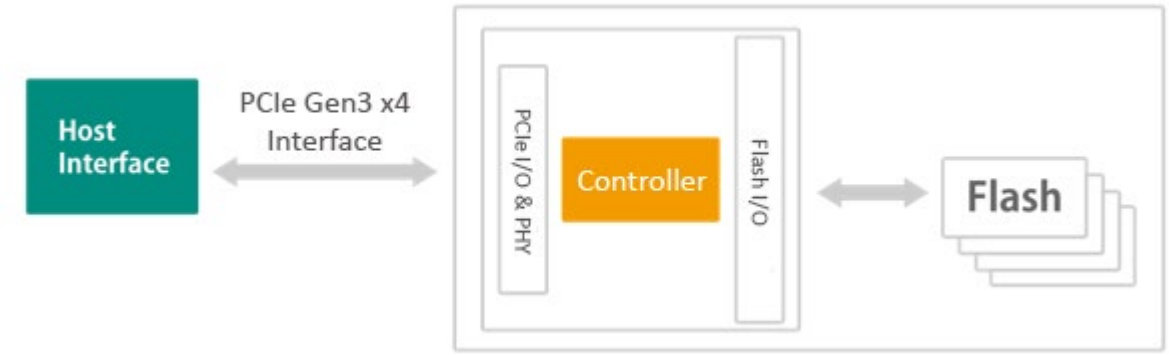
Utilizing 3D NAND technology for capacities up to 1TB and providing greater power efficiency than 2D NAND, PT230-M242 is equipped with an LDPC (Low-Density Parity Check) ECC engine to enhance endurance and improve data reliability. It also features a built-in thermal sensor to monitor SSD temperature via S.M.A.R.T commands and incorporates thermal throttling to dynamically adjust frequency scaling, ensuring data reliability and sustained performance under overheating conditions.

To further mitigate heat-related damage, PT230-M242 integrates a heat spreader that efficiently transfers heat while maintaining high-speed performance. Additionally, to ensure stable operation in high-vibration and extreme environmental conditions, it incorporates Sidefill technology to enhance product reliability and resistance to various thermal and mechanical shocks. For highly-intensive applications, End-to-End Data Protection ensures data integrity at multiple points along the data transfer path, providing reliable data delivery.

In terms of security, PT230-M242 offers robust data protection with Advanced Encryption Standard to safeguard against unauthorized access. It also incorporates various advanced features, including bad block management, DataDefender, TRIM, page mapping, Hyper Cache technology, DataRAID, Smart Read Refresh, and power saving modes.

With exceptional performance, proven reliability, and enhanced data protection, PT230-M242 is an ideal storage or cache solution for a variety of applications, including industrial, imaging, computing, and enterprise markets.

2. Functional Block



Note: The actual number of NAND flash used on Apacer PT230-M242 varies from capacities. The illustration is for reference only.

Figure 2-1 Functional Block Diagram

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3. Pin Assignments

This connector does not support hot plug capability. There are a total of 75 pins. 12 pin locations are used for mechanical key locations; this allows such a module to plug into Key M connectors.

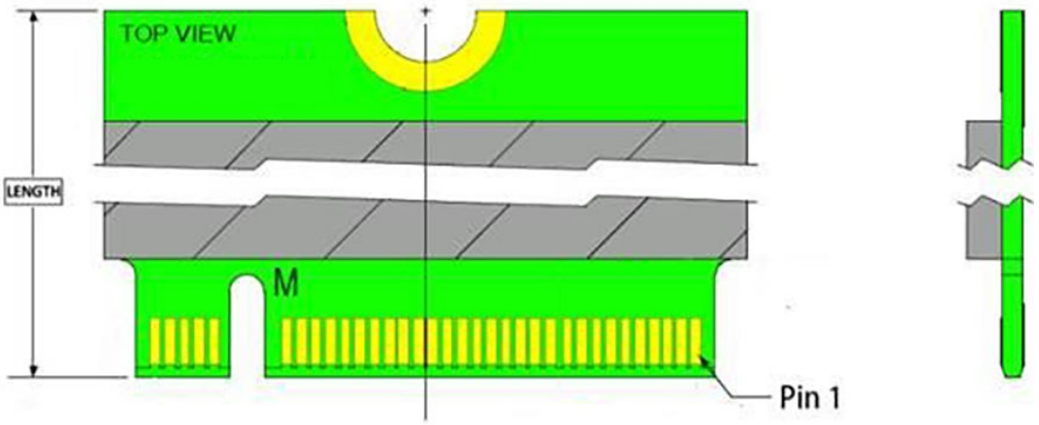


Figure 3-1 Pin Connectors

Table 3-1 Pin Assignments

Pin No.	Type	Description
1	GND	Ground
2	3.3 V	3.3V source
3	GND	Ground
4	3.3 V	3.3V source
5	PETn3	PCIe TX Differential signal defined by the PCI Express M.2 spec
6	PWRDIS (I)(0/1.8/3.3V)	No connect
7	PETp3	PCIe TX Differential signal defined by the PCI Express M.2 spec
8	PLN# (I)(0/1.8/3.3V)	No connect
9	GND	Ground
10	LED1#	Open drain, active low signal. These signals are used to allow the add-in card to provide status indicators via LED devices that will be provided by the system.
11	PERn3	PCIe RX Differential signal defined by the PCI Express M.2 spec
12	3.3 V	3.3V source
13	PERp3	PCIe RX Differential signals defined by the PCI Express M.2 spec
14	3.3 V	3.3V source
15	GND	Ground
16	3.3 V	3.3V source
17	PETn2	PCIe TX Differential signal defined by the PCI Express M.2 spec
18	3.3 V	3.3V source
19	PETp2	PCIe TX Differential signal defined by the PCI Express M.2 spec
20	NC	No connect
21	GND	Ground

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Table 3-1 Pin Assignments

Pin No.	Type	Description
22	VIO 1.8 V	No connect
23	PERn2	PCIe RX Differential signal defined by the PCI Express M.2 spec
24	NC	No connect
25	PERp2	PCIe RX Differential signal defined by the PCI Express M.2 spec
26	NC	No connect
27	GND	Ground
28	NC	Reserved for Apacer use only[1]
29	PETn1	PCIe TX Differential signal defined by the PCI Express M.2 spec
30	PLA_S3# (O)(0/1.8/3.3V)	Reserved for Apacer use only[1]
31	PETp1	PCIe TX Differential signal defined by the PCI Express M.2 spec
32	GND	No connect
33	GND	Ground
34	USB_D+	No connect
35	PERn1	PCIe RX Differential signal defined by the PCI Express M.2 spec
36	USB_D-	No connect
37	PERp1	PCIe RX Differential signal defined by the PCI Express M.2 spec
38	GND	No connect
39	GND	Ground
40	SMB_CLK (I/O)(0/1.8V)	No connect
41	PETn0	PCIe TX Differential signal defined by the PCI Express M.2 spec
42	SMB_DATA (I/O)(0/1.8V)	No connect
43	PETp0	PCIe TX Differential signal defined by the PCI Express M.2 spec
44	ALERT# (O)(0/1.8V)	No connect
45	GND	Ground
46	NC	No connect
47	PERn0	PCIe RX Differential signal defined by the PCI Express M.2 spec
48	NC	No connect
49	PERp0	PCIe RX Differential signal defined by the PCI Express M.2 spec
50	PERST# (I)(0/1.8V/3.3V)	PE-Reset is a functional reset to the card as specification. defined by the PCIe Mini CEM
51	GND	Ground
52	CLKREQ# (I/O)(0/1.8V/3.3V)	Clock Request is a reference clock request signal as defined by the PCIe Mini CEM specification; Also used by L1 PM Substates.
53	REFCLKn	PCIe Reference Clock signals (100 MHz) spec. defined by the PCI Express M.2
54	PEWAKE# (I/O)(0/1.8V/3.3V)	No connect
55	REFCLKp	PCIe Reference Clock signals (100 MHz) spec. defined by the PCI Express M.2
56	Reserved for MFG_DATA	Reserved for Apacer use only[1]
57	GND	Ground
58	Reserved for MFG_CLOCK	Reserved for Apacer use only[1]
59	Module Key M	Module Key
60	Module Key M	Module Key

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Table 3-1 Pin Assignments

Pin No.	Type	Description
61	Module Key M	Module Key
62	Module Key M	Module Key
63	Module Key M	Module Key
64	Module Key M	Module Key
65	Module Key M	Module Key
66	Module Key M	Module Key
67	NC	Reserved for Apacer use only[1]
68	SUSCLK (I)(0/1.8V/3.3V)	No connect
69	PEDET	No connect
70	3.3 V	3.3V source
71	GND	Ground
72	3.3 V	3.3V source
73	VIO_CFG (O)	Ground
74	3.3 V	3.3V source
75	GND	Ground

Note:
1. Reserved by Apacer, please do not connect to a host.

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4. Product Specifications

4.1 Capacity

Table 4-1 Capacity Specifications

Capacity	Total bytes	Total LBA
64 GB	60,022,480,896	117,231,408
128 GB	120,034,123,776	234,441,648
256 GB	240,057,409,536	468,862,128
512 GB	480,103,981,056	937,703,088
1 TB	960,197,124,096	1,875,385,008

Notes:
- Display of total bytes varies from operating systems.
- 1 GB = 1,000,000,000 bytes; 1 sector = 512 bytes.
- LBA count addressed in the table above indicates total user storage capacity and will remain the same throughout the lifespan of the device. However, the total usable capacity of the SSD is most likely to be less than the total physical capacity because a small portion of the capacity is reserved for device maintenance usages.

4.2 Performance

Table 4-2 Performance Specifications

Capacity / Performance	64 GB	128 GB	256 GB	512 GB	1 TB
Sequential Read (MB/s)	750	1,495	3,030	3,650	3,500
Sequential Write (MB/s)	450	910	1,835	2,550	2,550
4K Random Read (IOPS)	25,000	49,000	98,000	328,000	290,000
4K Random Write (IOPS)	82,000	156,000	253,000	295,000	297,000

Notes:
- Results may differ from various flash configurations or host system setting.
- Sequential read/write is based on CrystalDiskMark 8.0.4 with file size 1,000MB.
- Random read/write is measured using IOMeter with Queue Depth 128.

4.3 Environmental Specifications

Table 4-3 Environmental Specifications

Parameter	Type	Specifications
Temperature	Operating (Tc)	0°C to 70°C
	Non-operating (Ta)	-55°C to 100°C
Vibration	Operating	7.69 GRMS, 20~2000 Hz/random (compliant with MIL-STD-810G)
	Non-operating	4.02 GRMS, 15~2000 Hz/random (compliant with MIL-STD-810G)
Shock	Operating	Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G)
	Non-operating	Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)

Notes:
- This Environmental Specification table indicates the conditions for testing the device. Real world usages may affect the results.

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- Tc: case temperature; Ta: ambient temperature. The operating temperature is determined by the case temperature. Adequate airflow is advisable as it enables the device to maintain optimal temperatures, especially in environments with heavy workloads.

4.4 Mean Time Between Failures (MTBF)

Mean Time Between Failures (MTBF) is predicted based on reliability data for the individual components in PT230-M242. The prediction result for PT230-M242 is more than 3,000,000 hours.

Note: The MTBF is predicated and calculated based on “Telcordia Technologies Special Report, SR-332, Issue 3” method.

4.5 Certification and Compliance

- CE
- UKCA
- FCC
- RoHS
- MIL-STD-810G

4.6 Endurance

The endurance of a storage device is predicted by Drive Writes Per Day based on several factors related to usage, such as the amount of data written into the drive, block management conditions, and daily workload for the drive. Thus, key factors, such as Write Amplifications and the number of P/E cycles, can influence the lifespan of the drive.

Table 4-4 Endurance Specifications

Capacity	Drive Writes Per Day
64 GB	2.28
128 GB	2.05
256 GB	2.17
512 GB	2.01
1 TB	1.99

Notes:

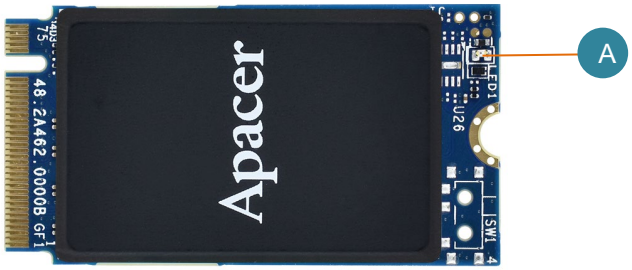
- This estimation complies with JEDEC JESD-219, enterprise endurance workload of random data with payload size distribution.
- Flash vendor guaranteed 3D NAND TLC P/E cycles: 3K
- WAF may vary from capacity, flash configurations and writing behavior on each platform.
- 1 Terabyte = 1,024GB
- DWPD (Drive Writes Per Day) is calculated based on the number of times that user overwrites the entire capacity of an SSD per day of its lifetime during the warranty period. (3D NAND TLC warranty: 3 years)

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4.7 LED Indicator Behavior

Table 4-5 LED Behavior

Location	LED	Description
LED A	DAS	LED blinks when the drive is being accessed



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5. Flash Management

5.1 Error Correction/Detection

PT230-M242 implements a hardware ECC scheme, based on the Low Density Parity Check (LDPC). LDPC is a class of linear block error correcting code which has apparent coding gain over BCH code because LDPC code includes both hard decoding and soft decoding algorithms. With the error rate decreasing, LDPC can extend SSD endurance and increase data reliability while reading raw data inside a flash chip.

5.2 Bad Block Management

Current production technology is unable to guarantee total reliability of NAND flash memory array. When a flash memory device leaves factory, it comes with a minimal number of initial bad blocks during production or out-of-factory as there is no currently known technology that produce flash chips free of bad blocks. In addition, bad blocks may develop during program/erase cycles. Since bad blocks are inevitable, the solution is to keep them in control. Apacer flash devices are programmed with ECC, page mapping technique and S.M.A.R.T to reduce invalidity or error. Once bad blocks are detected, data in those blocks will be transferred to free blocks and error will be corrected by designated algorithms.

5.3 Global Wear Leveling

Flash memory devices differ from Hard Disk Drives (HDDs) in terms of how blocks are utilized. For HDDs, when a change is made to stored data, like erase or update, the controller mechanism on HDDs will perform overwrites on blocks. Unlike HDDs, flash blocks cannot be overwritten and each P/E cycle wears down the lifespan of blocks gradually. Repeatedly program/erase cycles performed on the same memory cells will eventually cause some blocks to age faster than others. This would bring flash storages to their end of service term sooner. Global wear leveling is an important mechanism that levels out the wearing of all blocks so that the wearing-down of all blocks can be almost evenly distributed. This will increase the lifespan of SSDs.

5.4 DataDefender™

Apacer's DataDefender is an advanced technology of power failure management which combines both firmware and hardware mechanisms to ensure data integrity. When power disruption occurs, the low voltage detector will be triggered. When this happens, the SSD's protection mechanism is activated and cuts off data transmission from the host. Once the power supply is resumed, the firmware protection mechanism will ensure the integrity of the firmware as well as the data already written into the NAND flash media.

5.5 TRIM

TRIM is a feature which helps improve the read/write performance and speed of solid-state drives (SSD). Unlike hard disk drives (HDD), SSDs are not able to overwrite existing data, so the available space gradually becomes smaller with each use. With the TRIM command, the operating system can inform the SSD which blocks of data are no longer in use and can be removed permanently. Thus, the SSD will perform the erase action, which prevents unused data from occupying blocks all the time.

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5.6 Flash Translation Layer – Page Mapping

Page mapping is an advanced flash management technology whose essence lies in the ability to gather data, distribute the data into flash pages automatically, and then schedule the data to be evenly written. Page-level mapping uses one page as the unit of mapping. The most important characteristic is that each logical page can be mapped to any physical page on the flash memory device. This mapping algorithm allows different sizes of data to be written to a block as if the data is written to a data pool and it does not need to take extra operations to process a write command. Thus, page mapping is adopted to increase random access speed and improve SSD lifespan, reduce block erase frequency, and achieve optimized performance and lifespan.

5.7 Hyper Cache Technology

Apacer proprietary Hyper Cache technology uses a portion of the available capacity as SLC (1bit-per-cell) NAND flash memory, called Hyper cache mode. When data is written to SSD, the firmware will direct the data to Hyper Cache mode, providing excellent performance to handle various scenarios in industrial use.

5.8 DataRAID™

Apacer's DataRAID algorithm applies an additional level of protection and error-checking. Using this algorithm, a certain amount of space is given over to aggregating and resaving the existing parity data used for error checking. So, in the event that data becomes corrupted, the parity data can be compared to the existing uncorrupted data and the content of the corrupted data can be rebuilt.

5.9 Smart Read Refresh™

Apacer's Smart Read Refresh plays a proactive role in avoiding read disturb errors from occurring to ensure health status of all blocks of NAND flash. Developed for read-intensive applications in particular, Smart Read Refresh is employed to make sure that during read operations, when the read operation threshold is reached, the data is refreshed by re-writing it to a different block for subsequent use.

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6. NVMe Support Features

6.1 NVMe Secure Erase

NVMe Secure Erase is an NVMe drive sanitize command currently embedded in most of the storage drives. Defined in NVMe specifications, NVMe Secure Erase is part of Format NVM command that allows storage drives to erase all user data areas. The erase process usually runs on the firmware level as most of the NVMe-based storage media currently in the market are built-in with this command. NVMe Secure Erase can securely wipe out the user data in the drive and protects it from malicious attack.

6.2 Host Memory Buffer

Host Memory Buffer (HMB) allows HOST to allocate system memory for SSD's exclusive use in order to provide better performance and endurance, especially for DRAMless solutions.

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7. Security and Reliability Features

7.1 Advanced Encryption Standard

The Advanced Encryption Standard (AES) is a widely adopted encryption specification for securing electronic data, used by the U.S. government since 2001 and prevalent in embedded computing. AES employs symmetric encryption, meaning the same key is used for both encrypting and decrypting data, ensuring information remains inaccessible without the key. In flash memory applications, AES 256-bit hardware encryption is the standard for protecting sensitive data, offering superior performance, reliability, and security compared to software-based methods. By utilizing a dedicated processor within the controller, hardware encryption significantly speeds up encryption and decryption processes, making it highly efficient for safeguarding confidential information.

7.2 Thermal Sensor

Apacer Thermal Sensor is a digital temperature sensor with serial interface. By using designated pins for transmission, storage device owners are able to read temperature data.

7.3 Thermal Throttling

Thermal throttling can monitor the temperature of the SSD equipped with a built-in thermal sensor via S.M.A.R.T. commands. This method can ensure the temperature of the device stays within temperature limits by drive throttling, i.e. reducing the speed of the drive when the device temperature reaches the threshold level, so as to prevent overheating, guarantee data reliability, and prolong product lifespan. When the temperature exceeds the maximum threshold level, thermal throttling will be triggered to reduce performance step by step to prevent hardware components from being damaged. Performance is only permitted to drop to the extent necessary for recovering a stable temperature to cool down the device's temperature. Once the temperature decreases to the minimum threshold value, transfer speeds will rise back to its optimum performance level.

7.4 End-to-End Data Protection

End-to-End Data Protection is a feature implemented in Apacer SSD products that extends error control to cover the entire path from the host computer to the drive and back, and that ensures data integrity at multiple points in the path to enable reliable delivery of data transfers. Unlike ECC which does not exhibit the ability to determine the occurrence of errors throughout the process of data transmission, End-to-End Data Protection allows SSD controller to identify an error created anywhere in the path and report the error to the host computer before it is written to the drive. This error-checking and error-reporting mechanism therefore guarantees the trustworthiness and reliability of the SSD.

7.5 Sidefill

Apacer's Sidefill technology strengthens the connections between solder joints and their board, making them more robust and vibration-resistant. It also allows for heat dissipation to offset thermal damage.

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7.6 Heat Spreader

Apacer's patented graphene heat spreader is an advanced thermal solution designed to improve heat dissipation for NAND Flash components. It features a stacked structure encapsulated with insulating material, effectively isolating the conductive layer from surrounding electronic components to prevent short circuits. By efficiently transferring heat to a fluid medium, the design ensures stable high-speed SSD performance, reduces the risk of thermal-related failures, and enhances overall product reliability.

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8. Software Interface

8.1 Command Set

Table 8-1 summarizes the commands supported by PT230-M242.

Table 8-1 Admin Commands

Opcode	Command Description
00h	Delete I/O Submission Queue
01h	Create I/O Submission Queue
02h	Get Log Page
04h	Delete I/O Completion Queue
05h	Create I/O Completion Queue
06h	Identify
08h	Abort
09h	Set Features
0Ah	Get Features
0Ch	Asynchronous Event Request
10h	Firmware Activate
11h	Firmware Image Download
14h	Device Self-test

Table 8-2 Admin Commands – NVM Command Set Specific

Opcode	Command Description
80h	Format NVM
84h	Sanitize

Table 8-3 NVM Commands

Opcode	Command Description
00h	Flush
01h	Write
02h	Read
04h	Write Uncorrectable
05h	Compare
09h	Dataset Management

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8.2 S.M.A.R.T.

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is an open standard that allows a hard disk drive to automatically detect its health and report potential failures. When a failure is recorded by SMART, users can choose to replace the drive to prevent unexpected outage or data loss. Moreover, SMART can inform users of impending failures while there is still time to perform proactive actions, such as copy data to another device.

Table 8-4 SMART (02h)

Byte	Length	Description
0	1	Critical Warning
1-2	2	Composite Temperature
3	1	Available Spare
4	1	Available Spare Threshold
5	1	Percentage Used (Average Erase Count / P/E Cycle Count)
6-31	26	Reserved
32-47	16	Data Units Read
48-63	16	Data Units Written
64-79	16	Host Read Commands
80-95	16	Host Write Commands
96-111	16	Controller Busy Time
112-127	16	Power Cycles
128-143	16	Power On Hours
144-159	16	Unsafe Shutdowns
160-175	16	Media and Data Integrity Errors
176-191	16	Number of Error Information Log Entries
192-195	4	Warning Composite Temperature Time
196-199	4	Critical Composite Temperature Time
200-201	2	Temperature Sensor 1: Controller Temperature
202-203	2	Temperature Sensor 2: PCB Temperature
204-205	2	Temperature Sensor 3: NAND Flash Temperature
206-207	2	Temperature Sensor 4
208-209	2	Temperature Sensor 5
210-211	2	Temperature Sensor 6
212-213	2	Temperature Sensor 7
214-215	2	Temperature Sensor 8
216-511	296	Reserved

Note: Temperature display of the Temperature Sensor from 1 to 8 (corresponding bytes from 200 to 215) is not supported if the return value is 0h.

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Table 8-5 SMART (C0h)

Byte	Length	Description
0-255	256	Reserved
256-257	2	SSD Protect Mode
258-261	4	Host Read UNC Count
262-265	4	Reserved
266-269	4	CRC Error Count
270-273	4	Total Early Bad Block Count
274-277	4	Total Later Bad Block Count
278-281	4	Max Erase Count
282-285	4	Average Erase Count
286-289	4	Program Fail Count
290-293	4	Erase Fail Count
294-301	8	Flash Write Sector
302-305	4	Total Spare Block
306-309	4	Current Spare Block
310-313	4	Read Retry Count
314-511	210	Reserved

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9. Electrical Specifications

9.1 Operating Voltage

Table 9-1 Operating Range

Item	Range
Supply Voltage	3.3V ± 5%

9.2 Power Consumption

Table 9-2 Power Consumption

Capacity / Mode	Unit	64 GB	128 GB	256 GB	512 GB	1 TB
Active (Max.)	mA	510	685	1,065	1,225	1,230
Idle		195	195	200	190	195

Notes:
- All values are typical and may vary depending on flash configurations or host system settings.
- Power consumption is measured using CrystalDiskMark 8.0.4 with file size 1,000MB.

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10. Mechanical Specifications

10.1 Single-sided Dimensions

Table 10-1 Single-sided Physical Dimensions

Parameter	Unit	64 GB	128 GB
Length	mm	42.00 ± 0.15	
Width		22.00 ± 0.15	
Height (Max.)		2.58	

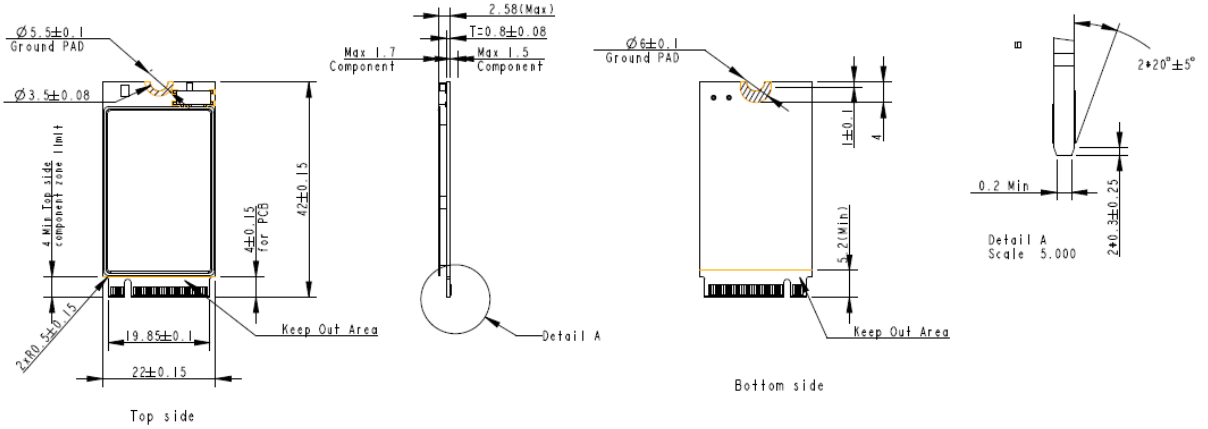


Figure 10-1 Single-sided Physical Dimensions

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10.2 Double-sided Dimensions

Table 10-2 Double-sided Physical Dimensions

Parameter	Unit	256 GB	512 GB	1 TB
Length	mm	42.00 ± 0.15		
Width		22.00 ± 0.15		
Height (Max.)		4.08		

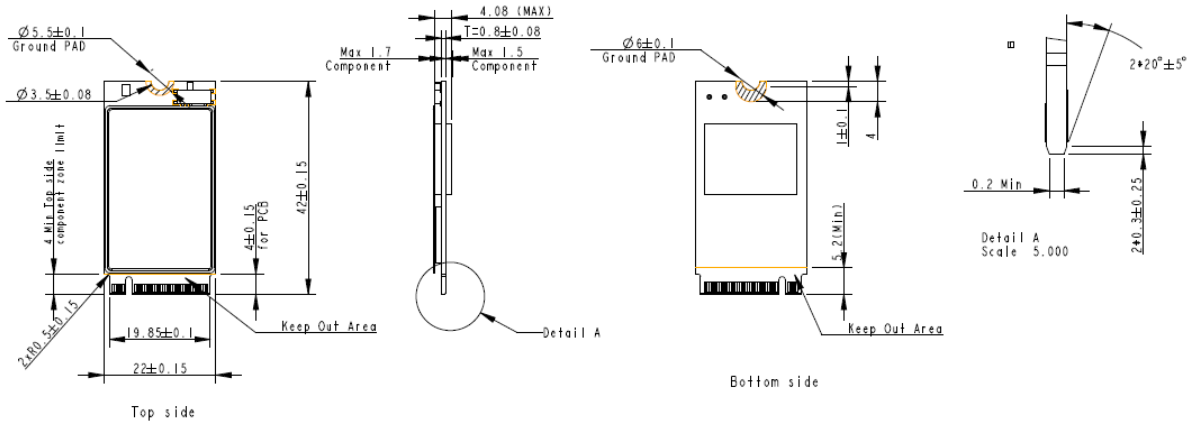


Figure 10-2 Double-sided Physical Dimensions

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11. Product Ordering Information

11.1 Product Code Designations

Code	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
	B	7	2	.	2	3	C	X	G	X	.	0	0	1	1	7

Code 1-3 (Product Line & Form Factor)	PCIe M.2 2242
Code 5-6 (Model/Solution)	PT230-M242
Code 7-8 (Product Capacity)	CG: 64GB CH: 128GB CJ: 256GB CK: 512GB CL: 1TB
Code 9 (Flash Type & Product Temp)	3D TLC Standard Temperature
Code 10 (Product Spec)	V: Single-sided M key with graphene U: Double-sided M key with graphene
Code 12-14 (Version Number)	Random numbers generated by system
Code 15-16 (Firmware Version)	Thermal sensor

11.2 Valid Combinations

Capacity	Part Number
64GB	B72.23CGGV.00117
128GB	B72.23CHGV.00117
256GB	B72.23CJGU.00117
512GB	B72.23CKGU.00117
1TB	B72.23CLGU.00117

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Revision History

Revision	Description	Date
1.0	Initial release	4/30/2025
1.1	Updated NVMe version from 1.3 to 1.4 on the Specifications Overview page and 1. General Description	5/5/2025
1.2	Modified the supported single-/double-sided capacities in 10. Mechanical Specifications	2/10/2026
1.3	- Updated the front-view product image on the cover and 4.7 LED Indicator Behavior - Updated the technology description of heat spreader at 7.6 Heat Spreader - Updated 10. Mechanical Specifications	3/26/2026
1.4	- Added 64GB support - Updated Performance, Endurance, and Power Consumption on the Specifications Overview page, Table 4-2, 4-4 and 9-2 - Updated 11. Product Ordering Information due to firmware change	4/27/2026

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